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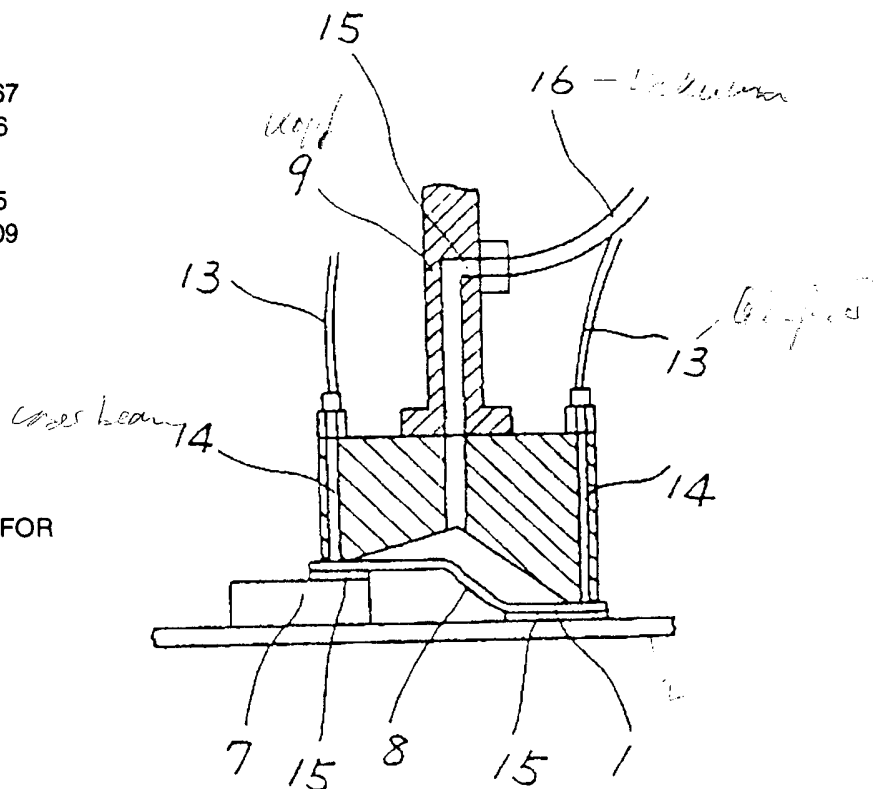
APPLICATION DATE : 27-03-85
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APPLICANT : HITACHI LTD;

INVENTOR : FUJIMOTO MINORU;

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TITLE : LASER SOLDERING DEVICE FOR FLEXIBLE CIRCUIT BOARD



ABSTRACT : PURPOSE: To easily solder by flexible circuit board the space between printing boards having differential step by forming the recess with angles on the tip of absorption part and by facilitating the transfer of flexible circuit board and the positioning to the soldering part.

CONSTITUTION: The recess having angles is formed on the tip of the absorption part of a laser irradiating head 9, exhausted by the tube 16 for evacuation and a flexible circuit substrate 8 is absorbed and fixed thereto. The vacuum absorption is stopped by placing the flexible circuit substrate 8 on the stepped substrates 1, 2 with the movement of the laser irradiating head 9. The substrates 1, 2 and flexible circuit substrate 8 are soldered by making laser beam 14 incident from irradiating aperture and by melting the solder paste 15 coated on the substrates 1, 2 in advance.

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